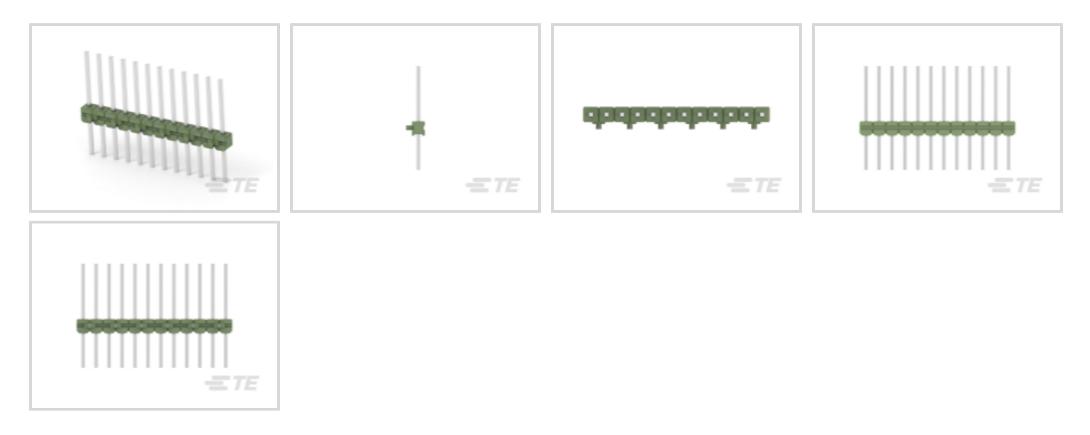
1-827313-2 - ACTIVE

AMPMODU | AMPMODU Headers

TE Internal #: 1-827313-2 PCB Mount Header, Vertical, Board-to-Board, 12 Position, 2.54 mm [.1 in] Centerline, Breakaway, Tin, Through Hole - Solder, Signal, AMPMODU Headers

View on TE.com >

Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: 12

Number of Rows: 1

Features



Product Type Features

PCB Connector Assembly Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Breakaway
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Vertical
Number of Positions	12
Number of Rows	1
Board-to-Board Configuration	Parallel
Body Features	
Connector Profile	Standard
Primary Product Color	Green

PCB Mount Header, Vertical, Board-to-Board, 12 Position, 2.54 mm [.1 in] Centerline, Breakaway, Tin, Through Hole - Solder, Signal, AMPMODU Headers



Contact Features

PCB Contact Termination Area Plating Material Thickness	2 µm
Contact Shape & Form	Square
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Phosphor Bronze
Contact Mating Area Plating Material	Tin
Contact Type	Pin
Contact Current Rating (Max)	5 A
Termination Features	
Termination Post & Tail Length	10.8 mm[.425 in]
Termination Method to Printed Circuit Board	Through Hole - Solder
Mechanical Attachment	
Mating Alignment	Without
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount

Housing Features

Centerline (Pitch)	2.54 mm[.1 in]
Housing Material	PBT GV
Dimensions	
PCB Thickness (Recommended)	1.4 mm[.055 in]
Usage Conditions	
Housing Temperature Rating	Standard
Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Type	Box, Carton

PCB Mount Header, Vertical, Board-to-Board, 12 Position, 2.54 mm [.1 in] Centerline, Breakaway, Tin, Through Hole - Solder, Signal, AMPMODU Headers



Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 240°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-onreach

Compatible Parts

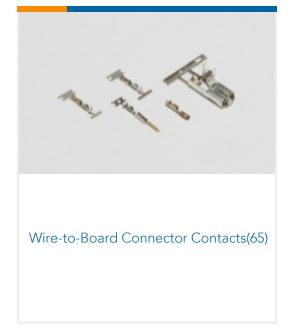


Also in the Series AMPMODU Headers

PCB Mount Header, Vertical, Board-to-Board, 12 Position, 2.54 mm [.1 in] Centerline, Breakaway, Tin, Through Hole - Solder, Signal, AMPMODU Headers







Customers Also Bought



Documents

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_1-827313-2_K.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_1-827313-2_K.3d_igs.zip

PCB Mount Header, Vertical, Board-to-Board, 12 Position, 2.54 mm [.1 in] Centerline, Breakaway, Tin, Through Hole - Solder, Signal, AMPMODU Headers



English

Customer View Model ENG_CVM_CVM_1-827313-2_K.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Agency Approvals

UL

English